Build Up HDI (Standard)

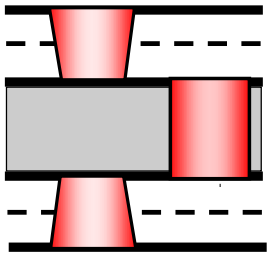
HDI04_1+2b+1_1,15_engl

4 - Layers

Core: 0,93 mm Cu 35/35 µm

WE-Articel No.:	**1 + 2B + 1**
Customer:	

WÜRTH ELEKTRONIK

layer description		configuration	Raw-Material	CU	PREPREG	Final Thickness	Customer requirements
Customer	WE					[µm]	[µm]
	TOP/VS		Foil	12 µm	1)	**12**	
					1 x 1080	**60**	
	2			12 µm		**35**	
			0,930 mm			**930**	
	3			12 µm		**35**	
					1 x 1080	**60**	
	BOT/RS		Foil	12 µm	1)	**12**	

1) copper thickness outer layers: appr. 55 µm

final lamination thickness:	**1,15**	+/-	0,09	mm			Date:	Engineer:	
thickness with electro plated Cu:	1,24	+/-	0,12	mm					
total thickness with soldermask	1,30	+/-	0,14	mm					
customer requirement		+/-		mm	point:				

total material thickness: 1144

Note: Lamination thickness for Prepregs depending on layout characteristics.

prepared: on	by	checked: on	by	approved: on	by	revision	page:
04.01.2006	**S. Keller**	04.05.2006	M.Kress	04.01.2006	R. Schönholz	00	6+